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(12) United States Design Patent

Standing et al.

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(54) **CONDUCTIVE CLIP FOR A SEMICONDUCTOR PACKAGE**

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(**) Term: **14 Years**

(21) Appl. No.: **29/188,754**

(22) Filed: **Aug. 22, 2003**

Related U.S. Application Data

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(51) **LOC (7) Cl.** **13-03**

(52) **U.S. Cl.** **D13/182**

(58) **Field of Search** D13/182; 174/52.1, 174/52.2; 257/666, 670, 678, 684, 690, 719, 776, 782, 796; 361/760, 771, 774, 792, 798, 820

(56) **References Cited**

U.S. PATENT DOCUMENTS

4,864,470 A	*	9/1989	Nishio	361/760
5,047,833 A		9/1991	Gould	
5,235,496 A	*	8/1993	Chomette et al.	361/764
5,451,544 A		9/1995	Gould	
D379,350 S	*	5/1997	Kerklaan	D13/182
5,814,884 A		9/1998	Davis et al.	
5,818,699 A	*	10/1998	Fukuoka	361/760
D407,382 S	*	3/1999	Acciaioli et al.	D13/182
5,904,499 A		5/1999	Pace	
6,107,680 A	*	8/2000	Hodges	257/680
6,137,158 A	*	10/2000	Cohen et al.	257/666

* cited by examiner

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(57) CLAIM

The ornamental design for a conductive clip for a semiconductor package, as shown and described.

DESCRIPTION

FIG. **1** is a perspective view of a conductive clip according to our design;

FIG. **2** is another perspective view of a conductive clip according to our design, the broken lines being included for illustrative purposes and forming no part of the claimed design;

FIG. **3** is a top plan view of a conductive clip according to our design;

FIG. **4** is a bottom plan view of a conductive clip according to our design, the broken lines being included for illustration purposes and forming no part of the claimed design;

FIG. **5** is a side elevational view of a conductive clip according to our design; and,

FIG. **6** is a side elevational view of a conductive clip according to our design.

1 Claim, 2 Drawing Sheets

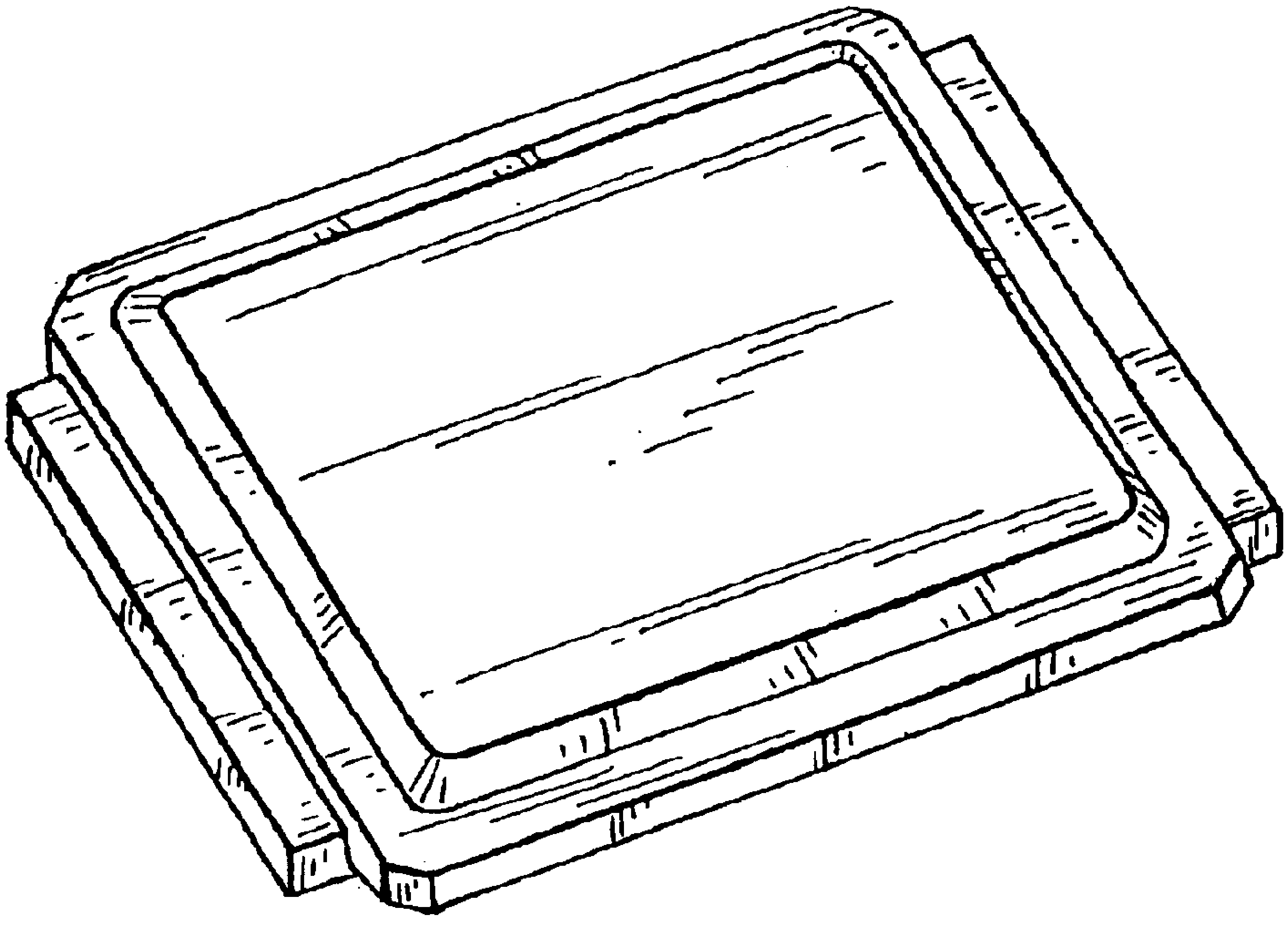
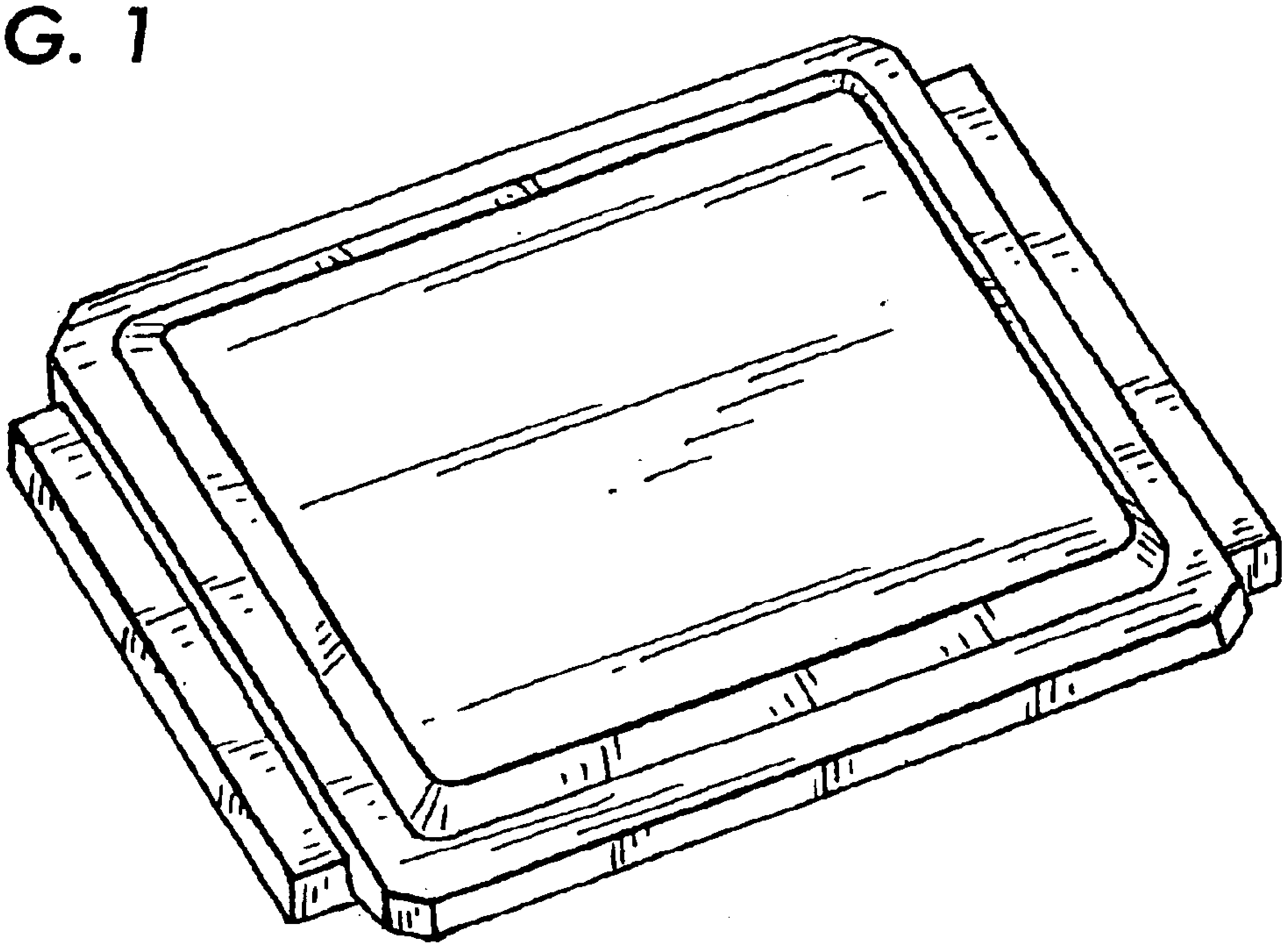


FIG. 1



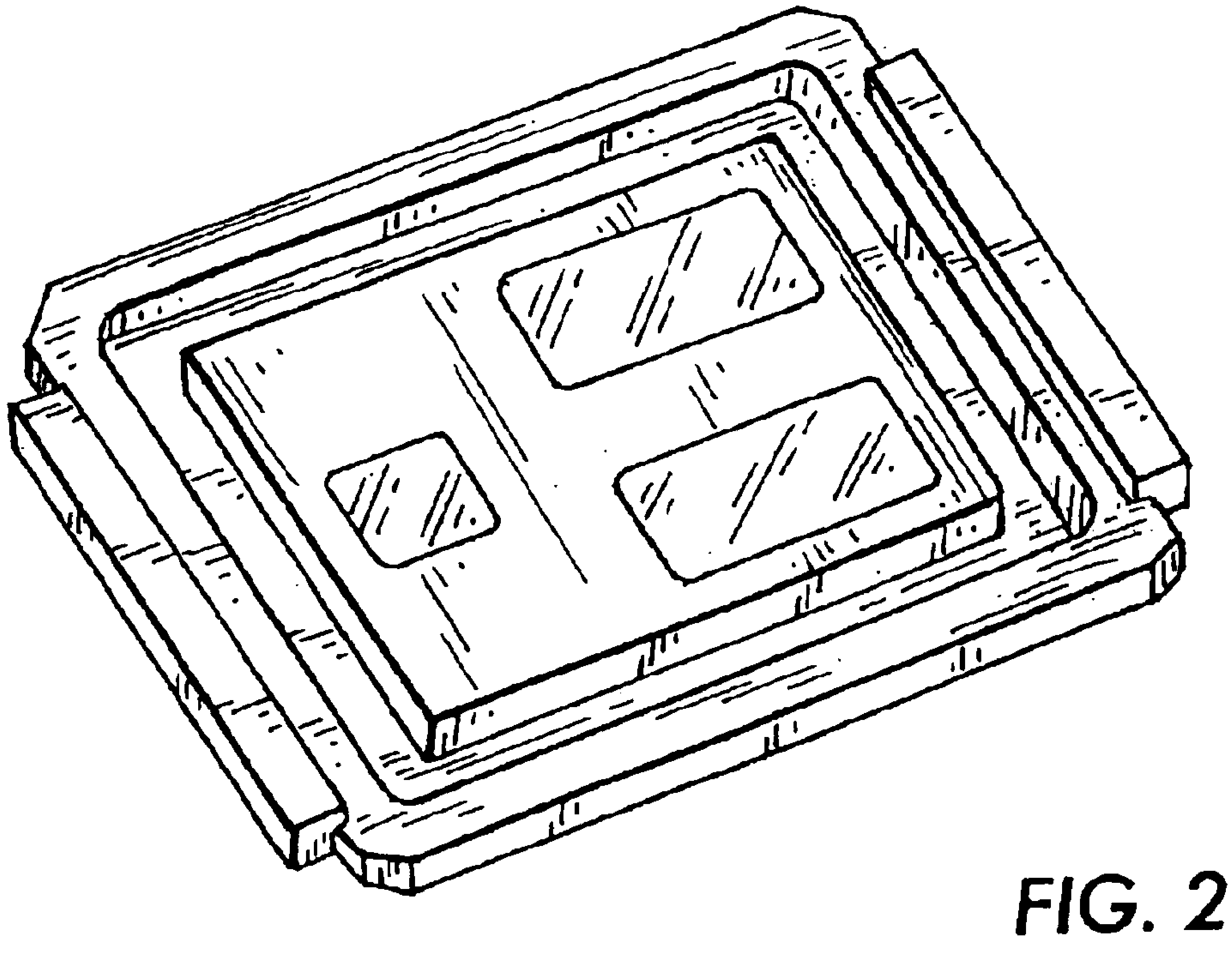


FIG. 2

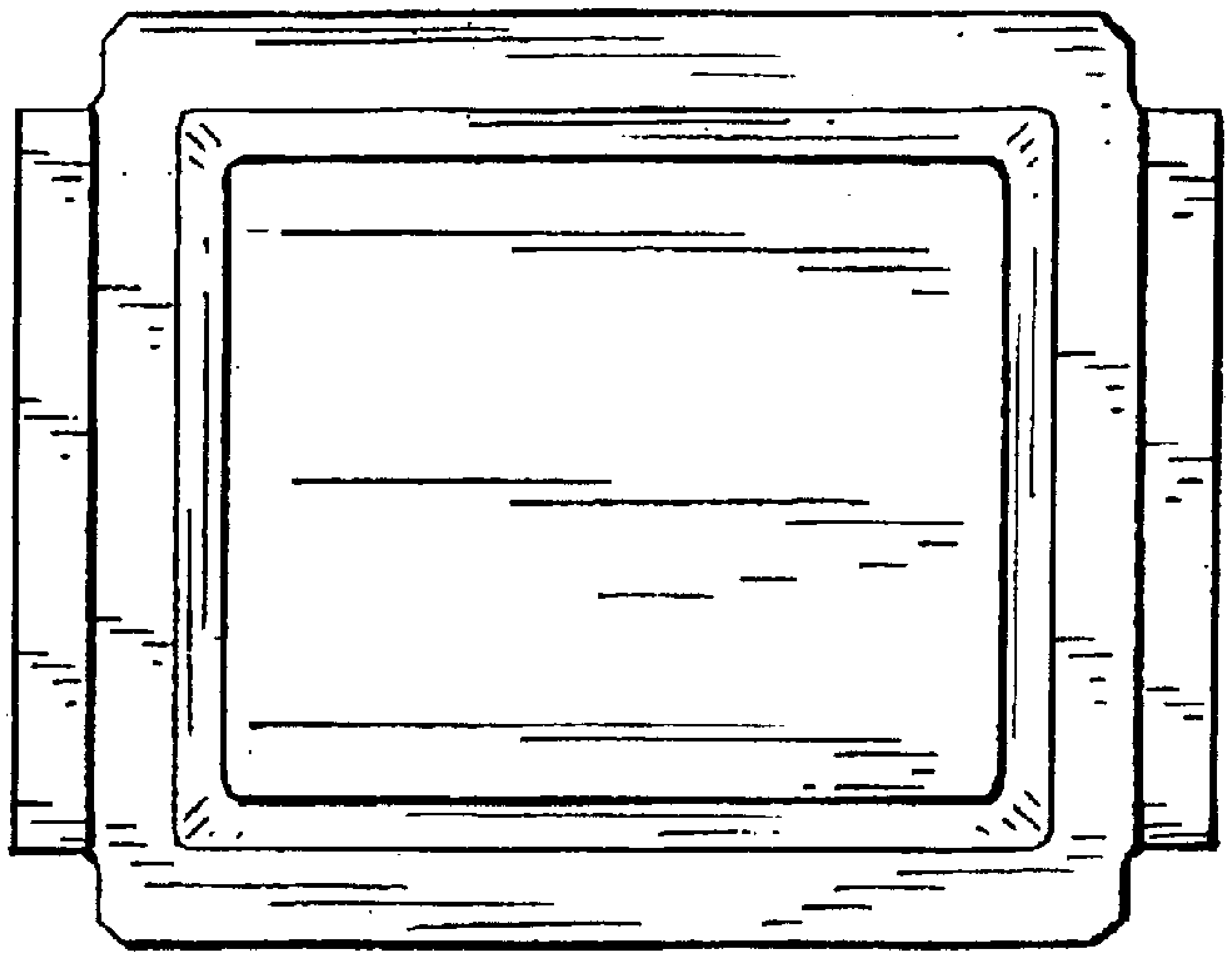


FIG. 3

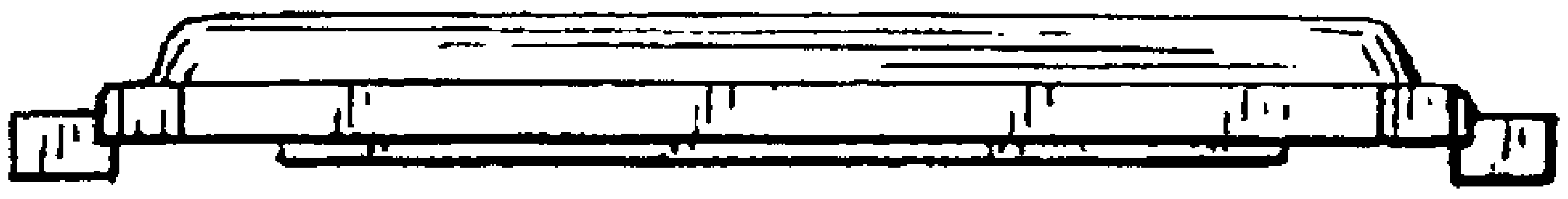


FIG. 5

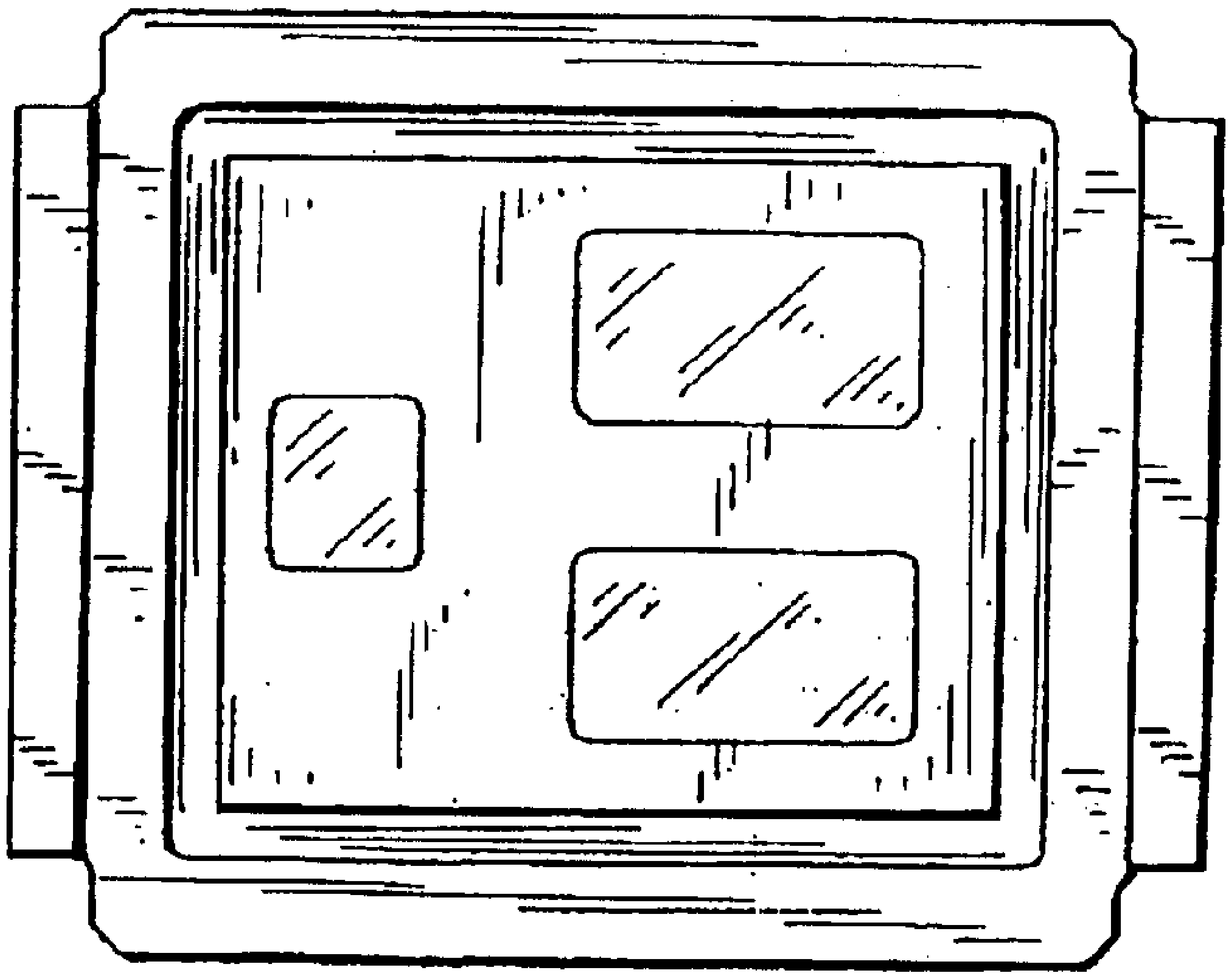


FIG. 4

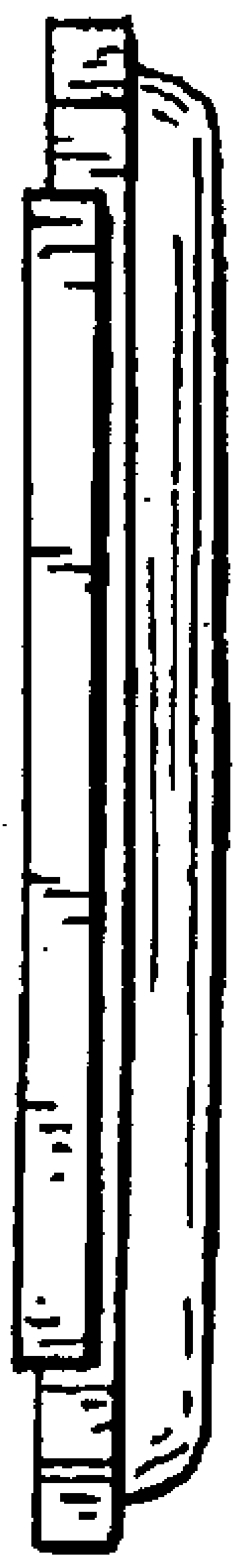


FIG. 6